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(54) Title: AUTOMATIC BLIND HAND-OFF TO CENTER WAFER REFERRING TO HEATER POCKET

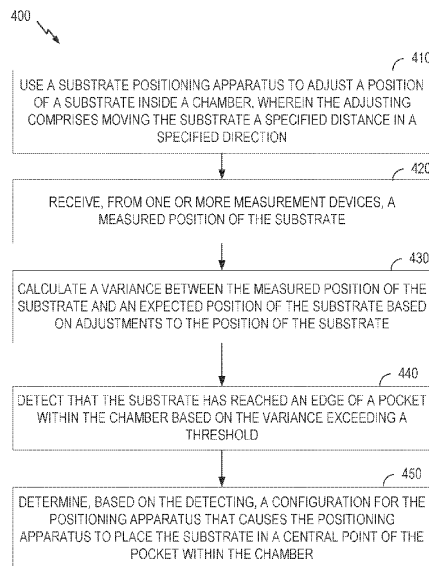


FIG. 4

(57) Abstract: Methods and devices for automatically adjusting the position of substrates are provided herein. Embodiments include using a substrate positioning apparatus to adjust a position of a substrate inside a chamber, wherein the adjusting comprises moving the substrate a specified distance in a specified direction. Embodiments further include receiving, from one or more measurement devices, a measured position of the substrate. Embodiments further include calculating a variance between the measured position of the substrate and an expected position of the substrate based on adjustments to the position of the substrate. Embodiments further include detecting that the substrate has reached an edge of a pocket inside the chamber based on the variance exceeding a threshold. Embodiments further include determining, based on the detecting, a configuration for the positioning apparatus that causes the positioning apparatus to place the substrate in a central point of the pocket.

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